

06-14-2005

Form PTO-1595 (Rev. 09/04)
OMB No. 0651-0027 (exp. 6/30/2005)U.S. DEPARTMENT OF COMMERCE
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103020853

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):

Ryoichi Watanabe

Execution Date(s): May 18, 2005

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: Samsung Electro-Mechanics Co., Ltd.

Internal Address:

Street Address:

314, Maetan-3dong
Youngtong-gu, Suwon-si

City: Kyunggi-do

State:

Country: Republic of Korea Zip: 443-743

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

A. Patent Application No.(s)

☒ This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Joseph R. Robinson
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6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☒ Enclosed
☐ None required (government interest not affecting title)

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9. Signature:

Marie Collozo
MARIE COLLOZO 44085

Signature

June 6, 2005

Date

Y. Jae Kim - 53,128

Name of Person Signing

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2

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PATENT
REEL: 016675 FRAME: 0316

ASSIGNMENT

This is an Assignment of the following rights, title and interest:

- ☐ United States of America rights, title and interest in the invention
☐ United States Patent Application Serial No. _____

Title of the Invention:

METHOD OF FABRICATING HIGH DENSITY PRINTED CIRCUIT BOARD

Inventor (assignor):

WATANABE, Ryoichi: Expo -Apt. 103-603, Jeonmin-dong, Yusung-gu, Daejeon, Korea

Assignee:

**SAMSUNG ELECTRO-MECHANICS CO., LTD.: 314, Maetan-3dong, Youngtong-gu, Suwon-si,
Kyunggi-do 443-743, Korea**

Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to the above-identified assignee;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said applications(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States, unto said Assignee.

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

Watanabe Ryoichi

Signature: WATANABE, Ryoichi

May 18, 2005

Date